Electrically Insulating, Thermally Conductive Phase Change Material

Features and Benefits

- Thermal impedance:
 0.71°C-in²/W (@25 psi)
- · Electrically isolating
- 65°C phase change compound coated on PEN film
- · Tack-free and scratch-resistant



Hi-Flow 625 is a film-reinforced phase change material. The product consists of a thermally conductive 65°C phase change compound coated on PEN film. Hi-Flow 625 is designed to be used as a thermal interface material between electronic power devices that require electrical isolation and a heat sink. The reinforcement makes Hi-Flow 625 easy to handle, and the 65°C phase change temperature of the coating material eliminates shipping and handling problems. The PEN film has a continuous use temperature of 150°C.

Hi-Flow 625 is tack-free and scratch-resistant at production temperature and does not require a protective liner in most shipping situations. The material has the thermal performance of 2-3 mil mica and grease assemblies.

| TYPICAL PROPERTIES OF HI-FLOW 625 | | | | | | |
|--|------------------|------|------------------|------|-------------|------|
| PRO PERTY | IMPERIAL VALUE | | METRIC VALUE | | TEST METHOD | |
| Color | Green | | Green | | Visual | |
| Reinforcement Carrier | PEN Film | | PEN Film | | _ | |
| Thickness (inch) / (mm) | 0.005 | | 0.127 | | ASTM D374 | |
| Elongation (%45° to W arp and Fill) | 60 | | 60 | | ASTM D882A | |
| Tensile Strength (psi) / (MPa) | 30,000 | | 206 | | ASTM D882A | |
| Continuous Use Temp (°F) / (°C) | 302 | | 150 | | _ | |
| Phase Change Temp (°F) / (°C) | 149 | | 65 | | ASTM D3418 | |
| ELECTRICAL | | | | | | |
| Dielectric Breakdown Voltage (Vac) | 4000 | | 4000 | | ASTM D149 | |
| Dielectric Constant (1000 Hz) | 3.5 | | 3.5 | | ASTM D150 | |
| Volume Resistivity (O hm-meter) | 10 ¹⁰ | | 10 ¹⁰ | | ASTM D257 | |
| Flame Rating | V-O | | V-O | | U.L. 94 | |
| THERMAL | | | | | | |
| Thermal Conductivity (W /m-K) (1) | 0.5 | | 0.5 | | ASTM D5470 | |
| THERMAL PERFORMANCE vs PRESSURE | | | | | | |
| Press | sure (psi) | 10 | 25 | 50 | 100 | 200 |
| TO -220 Thermal Performance (°C/W) | | 2.26 | 2.10 | 2.00 | 1.93 | 1.87 |
| Thermal Impedance (°C-in²/W) (2) | | 0.79 | 0.71 | 0.70 | 0.67 | 0.61 |
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1) This is the measured thermal conductivity of the Hi-Flow coating. It represents one conducting layer in a three-layer laminate. The Hi-Flow coatings are phase change compounds. These layers will respond to heat and pressure induced stresses. The overall conductivity of the material in post-phase change, thin film products is highly dependent upon the heat and pressure applied. This characteristic is not accounted for in ASTM D5470. Please contact Bergquist Product Management if adultan specifications are required.

Typical Applications Include:

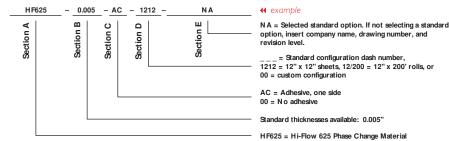
- · Spring / clip mounted
- · Power semiconductors
- · Power modules

Configurations Available:

- · Sheet form, die-cut parts and roll form
- · W ith or without pressure sensitive adhesive

Building a Part Number

Standard Options



Note: To build a part number, visit our website at www.bergquistcompany.com.

Hi- Flow®: U.S. Patents 6,197,859 and 5,950,066.



²⁾ The ASTM D5470 test fixture was used and the test sample was conditioned at 70°C prior to test. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.